

WHAT IS CLAIMED IS:

1. A process for manufacturing a flexible wiring board
comprising forming a wiring pattern and a reinforcing guide pattern
5 by etching a metal foil on an insulating substrate.

2. A flexible wiring board comprising a wiring pattern formed
of a desired metal on a film-like insulating substrate wherein a
reinforcing guide pattern having a same material as that of the
10 wiring pattern is formed on the insulating substrate.

3. The flexible wiring board according to claim 2 wherein
the guide pattern has a projecting reinforcing guide having a
thickness greater than that of the wiring pattern.

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4. The flexible wiring board according to claim 2 wherein
the guide pattern is formed as a frame shape surrounding the
periphery of the wiring pattern.

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5. The flexible wiring board according to claim 3 wherein
the guide pattern is formed as a frame shape surrounding the
periphery of the wiring pattern.

6. The flexible wiring board according to claim 2 wherein
25 the wiring pattern is formed a plurality of wiring patterns in a

desired arrangement and the guide pattern is formed as a grid shape.

7. The flexible wiring board according to claim 3 wherein
the wiring pattern is formed as a plurality of wiring patterns in
5 a desired arrangement and the guide pattern is formed as a grid
shape.

8. The flexible wiring board according to claim 4 wherein
the guide pattern has guide holes for positioning.

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9. The flexible wiring board according to claim 5 wherein
the guide pattern has guide holes for positioning.

10. The flexible wiring board according to claim 6 wherein
15 the guide pattern has guide holes for positioning.

11. The flexible wiring board according to claim 7 wherein
the guide pattern has guide holes for positioning.

12. The flexible wiring board according to claim 2 wherein
20 the wiring pattern has projecting electrodes.

13. The flexible wiring board according to claim 2 wherein
the wiring pattern has flat electrodes.

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14. The flexible wiring board according to claim 2 wherein a first wiring pattern is formed on one side of the insulating substrate, and a second wiring pattern is formed on an opposite side of the insulating substrate to the wiring pattern.

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15. The flexible wiring board according to claim 14 wherein the second wiring pattern has projecting electrodes.

16. The flexible wiring board of claim 14 wherein the second
10 wiring pattern has flat electrodes.

17. The flexible wiring board according to claim 2 wherein the reinforcing guide pattern is formed integral with the wiring pattern on the insulating substrate.

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